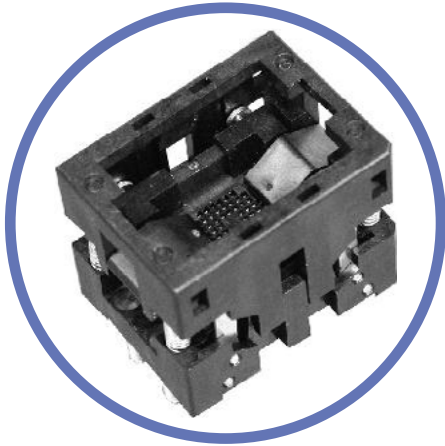


| 775E SERIES

COMPACT CSP/FBGA



Features

- 0.8mm Pitch
- Compression surface mount
- Z-axis compliant "U" shaped contact supports a wide variety of solder ball shape and composition
- Compact outline and low actuation force achieved through use of innovative latching mechanism
- Field exchangeable IC guide

MATERIALS & SPECIFICATIONS

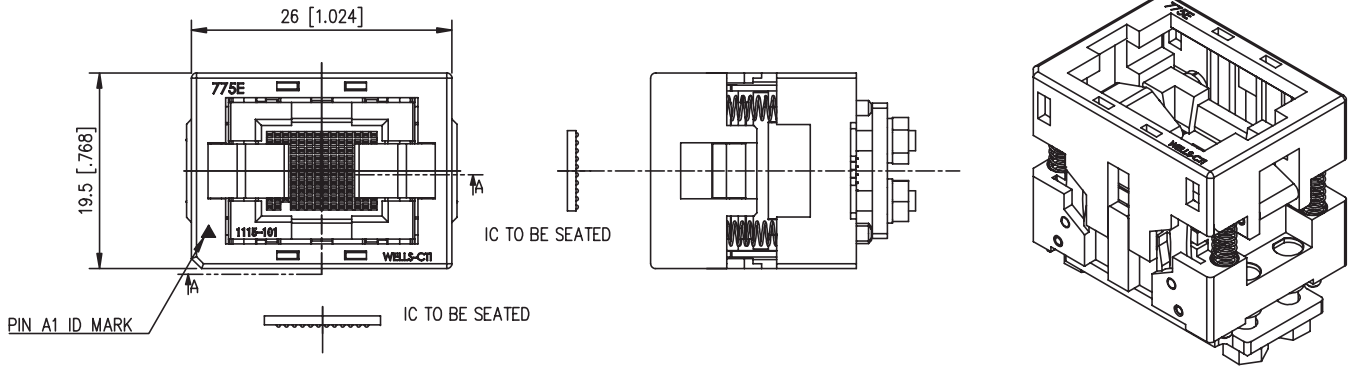
| | |
|---------------------------|------------------------------|
| Body Materials | PES, PEI, LCP, or Equivalent |
| Contact Material | Beryllium Copper Alloy |
| Contact Plating | Gold |
| Contact Force | 13 Gram Average |
| Contact Resistance | 200~300 mΩ |
| Temperature Rating | 150°C |
| Durability | 10,000 Cycles min. |

| Pitch e (mm) | Pin Count | Package Size (mm) | Pin Matrix. | Ball Dia. (mm) | Ball Height (mm) | Part Number |
|--------------|-----------|-------------------|-------------|----------------|------------------|--------------|
| 0.8 | 60 | 8X11.6 | 8X10 | 0.40 | 0.22 | 775E1060-101 |
| | 84 | 9X12 | 10X12 | 0.40 | 0.15 | 775E1084-101 |
| | 115 | 9X12 | 10X14 | 0.40 | 0.15 | 775E1115-101 |
| | 115 | 11X13 | 10X14 | 0.40 | 0.22 | 775E1115-102 |
| | 137 | 11X13 | 10X14 | 0.40 | 0.15 | 775E1137-101 |
| | 138 | 10X10 | 12X12 | 0.40 | 0.22 | 775E1138-101 |



DIMENSIONS AND DIAGRAMS

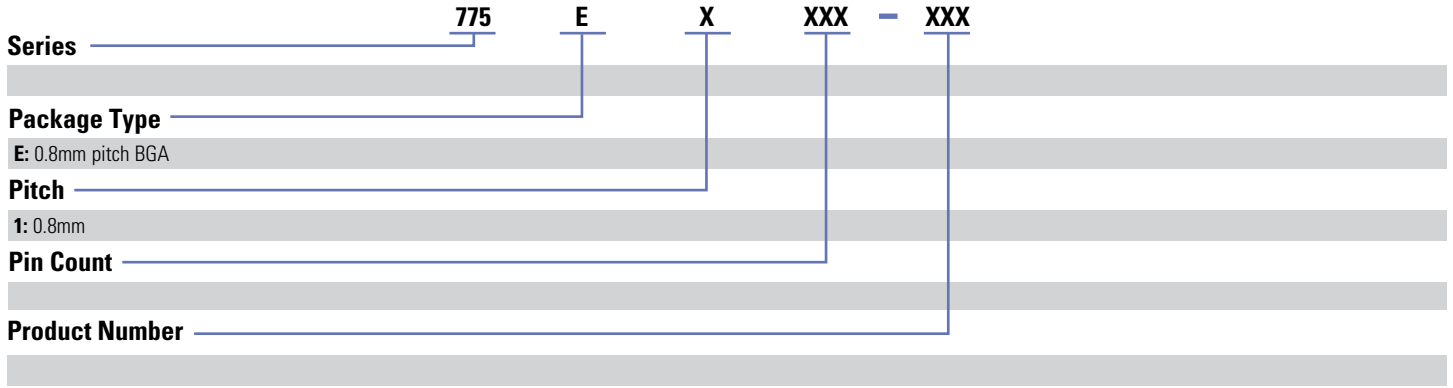
Dimensions in mm (Inches)





DESCRIPTION & ORDERING INFO

Example : 775 E X XXX-XXX



Revised 02/06/18

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